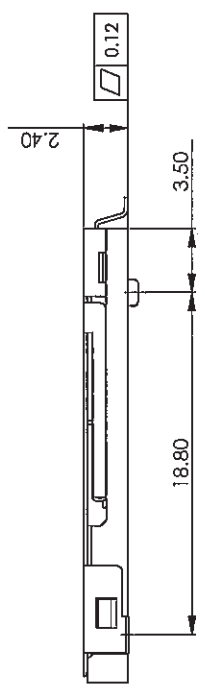


NOTES:  
 1. MATERIAL: HIGH TEMPERATURE THERMOPLASTIC, UL94-V0  
 COLOR: BLACK  
 CONTACT: COPPER ALLOY  
 COVER: STAINLESS STEEL  
 2. PLATING:  
 CONTACT AREA: GOLD OVER NICKEL  
 SOLDER AREA: TIN/LEAD OVER NICKEL  
 3. COPLANARITY MUST BE WITH IN 0.12mm  
 4. PART NO: MSU010-XX-5001

COLOR:  
 0 - BLACK  
 7 - IVORY

PLATING:  
 0 - GOLD FLASH  
 2 - 10"  
 UNLEAD PLATING:  
 A - GOLD FLASH  
 C - 10"



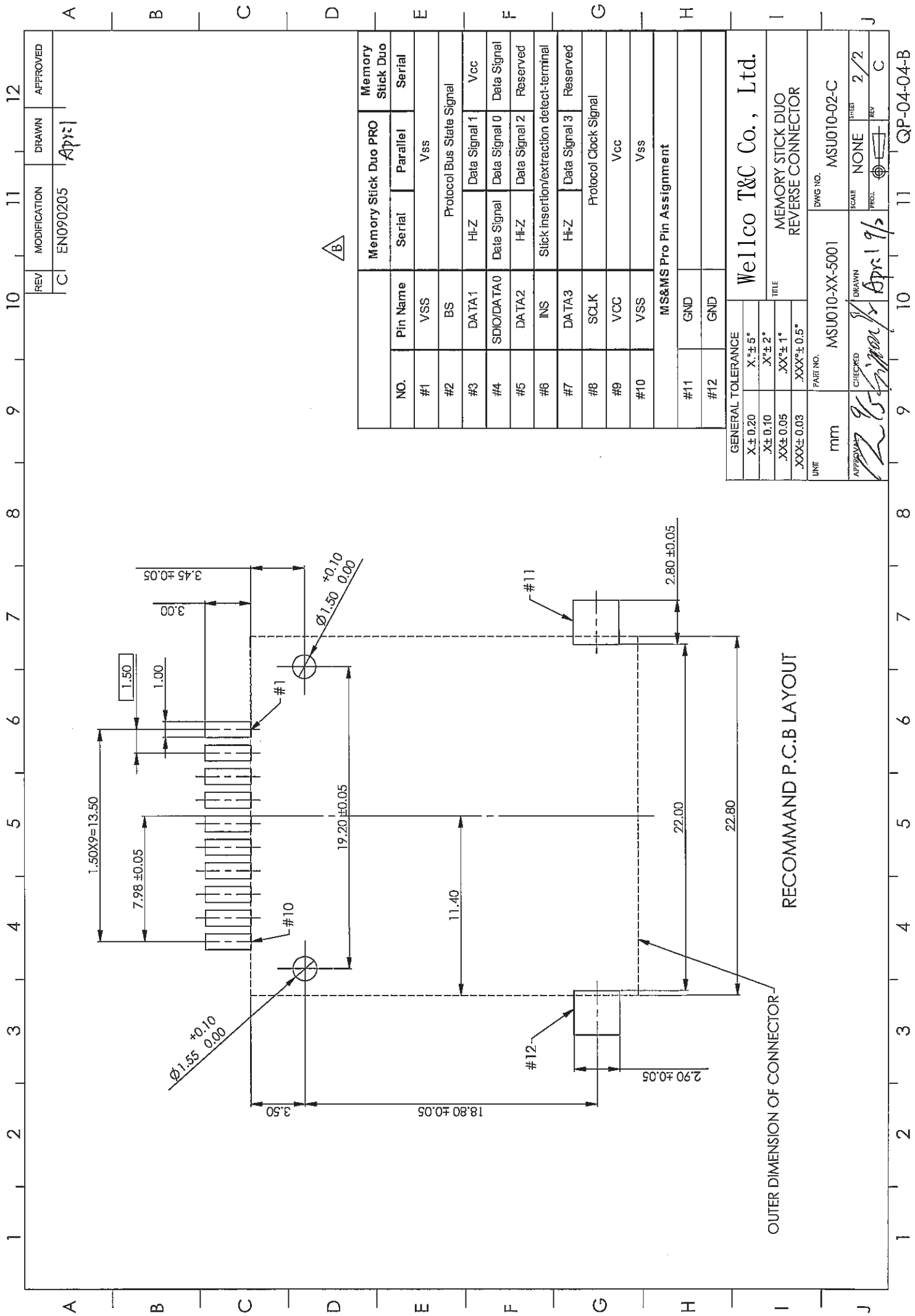
GENERAL TOLERANCE	
X ± 0.40	X° ± 5°
X ± 0.30	X° ± 2°
XX ± 0.20	XX° ± 1°
XXX ± 0.10	XXX° ± 0.5°

UNIT: mm  
 PART NO: MSU010-XX-5001  
 DWG NO: MSU010-02-C

Wellco T&C Co., Ltd.  
 MEMORY STICK DUO REVERSE CONNECTOR  
 TITLE

APPROVED	CHECKED	DRAWN	SCALE	SHEET
<i>[Signature]</i>	<i>[Signature]</i>	<i>[Signature]</i>	NONE	1/2
				C

QP-04-04-B



△ B

Memory Stick Duo PRO		Memory Stick Duo
NO.	Pin Name	Serial
#1	VSS	Parallel
#2	BS	Vss
#3	DATA 1	Protocol Bus State Signal
#4	SDIO/DATA0	HI-Z
#5	DATA2	Data Signal 1
#6	INS	Data Signal 0
#7	DATA3	HI-Z
#8	SCLK	Data Signal 2
#9	VCC	Reserved
#10	VSS	Stick insertion/extraction detect-terminal
MS&MS Pro Pin Assignment		
#11	GND	Data Signal 3
#12	GND	Protocol Clock Signal

GENERAL TOLERANCE	
X ± 0.20	X° ± 5°
X ± 0.10	X° ± 2°
XX ± 0.05	XX° ± 1°
XXX ± 0.03	XXX° ± 0.5°

UNIT	mm	PART NO.	MSU010-XX-5001	DWG. NO.	MSU010-02-C
APPROVED	<i>[Signature]</i>	CHECKED	<i>[Signature]</i>	SCALE	NONE
REV	C	MODIFICATION	EN090205	DATE	2/2
DRAWN	<i>[Signature]</i>	TITLE	MEMORY STICK DUO REVERSE CONNECTOR	REV	C

Wellco T&C Co., Ltd.

RECOMMEND P.C.B LAYOUT

OUTER DIMENSION OF CONNECTOR

QP-04-04-B